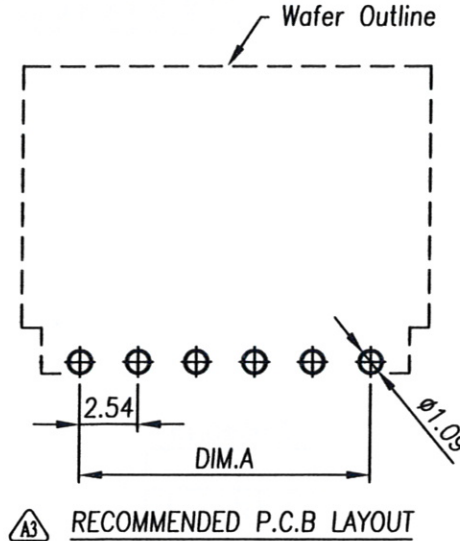
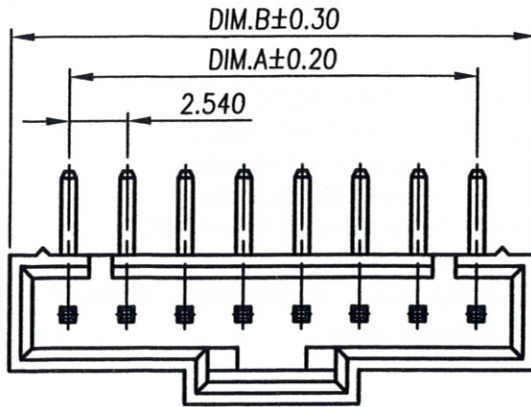


RoHS Compliant



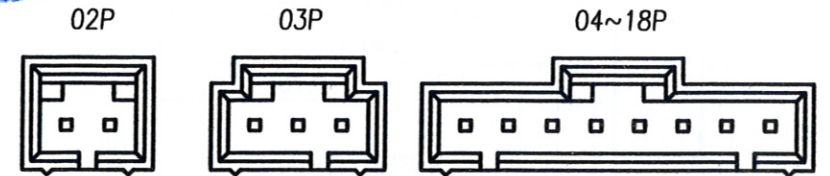
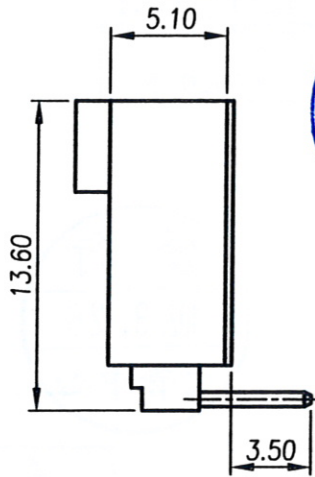
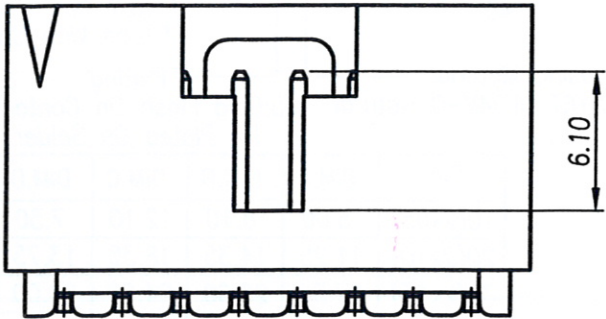
REV	MODIFICATION	DATE	DRAW
A1	Add Order Information & P/N	2010.08.23	Ivy
A2	Release To ECN20130303	2013.03.12	Seven
A3	Release To ECN20150201	2015.02.02	Michelle



Specification  
 1.Current Rating:2.5A AC/DC  
 2.Voltage Rating:250V AC/DC  
 3.Contact Resistance:20mΩ Max.  
 4.Insulation Resistance:1000MΩ Min. At 500V  
 5.Dielectric Withstanding Voltage:AC600V/Minute  
 6.Operating Temperature:-25°C~+85°C  
 Material:

1.Housing:Thermoplastic UL94V-0  
 2.Contact Pin:Copper Alloy SQ. Pin 0.64mm  
 Finish:  
 1.Housing:Black  
 2.Contact Pin:See P/N Option

Part No.: AD03801 XX 8 3 5 A  
 Number Of Pin: 02~18  
 Packing: 5:Bag  
 Housing Material: 8:PBT UL94V-0 Black  
 Plating: 3:Gold Flash Over Nickel



Pin	DIM.A	DIM.B	Pin	DIM.A	DIM.B	Pin	DIM.A	DIM.B
02	2.54	7.62	08	17.78	22.86	14	33.02	38.10
03	5.08	10.16	09	20.32	25.40	15	35.56	40.64
04	7.62	12.70	10	22.86	27.94	16	38.10	43.18
05	10.16	15.24	11	25.40	30.48	17	40.64	45.72
06	12.70	17.78	12	27.94	33.02	18	43.18	48.26
07	15.24	20.32	13	30.48	35.56			

**金上達科技股份有限公司**  
**GOLDENSUNDA TECHNOLOGY CO.,LTD**

TOLERANCE UNLESS OTHERWISE SPECIFIED  
 PROJ. TITLE: Wire To Board Wafer 2.54mm 90° DIP Single Row

.x± 0.35    x:± 2'    APR. C.F.Liao 20150202    PART NO. AD03801XX835A    DWG NO. AD03801XX835A

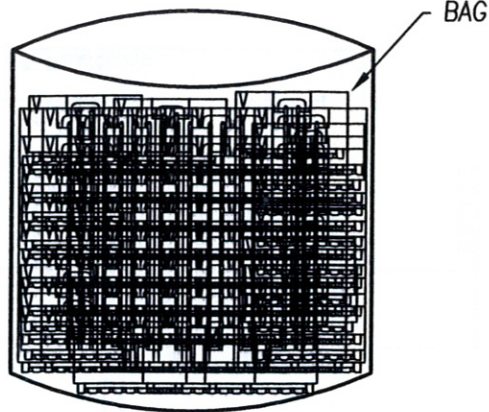
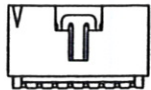
.xx± 0.25    .x:± 1'    CHK. Abel 20150202    UNITS: mm    CUSTOMER DRAWING

.xxx± 0.15    .xx:± 0.5'    DRA. Michelle 20150202    SIZE: A4    SCALE 3:1    SHEET 1 / 2    REV A3    V

RoHS Compliant



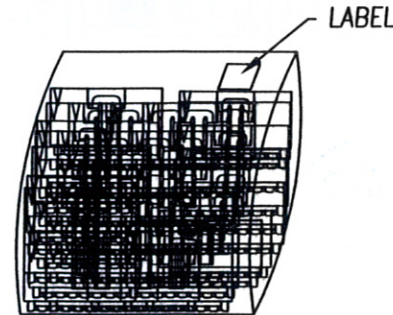
REV	MODIFICATION	DATE	DRAW
A1	Add Order Information,P/N	2010.08.23	Ivy
A2	Release To ECN20130303	2013.03.12	Michelle
A3	Release To ECN20150201	2015.02.02	Michelle



BAG

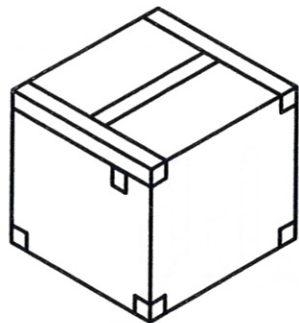
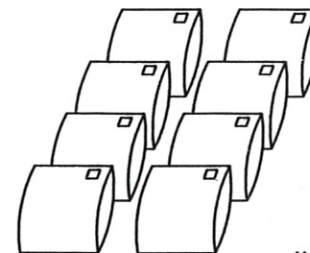
CONNECTOR INTO THE BAG

PIN	Q'TY
02~05	1000
06~11	500
12	250

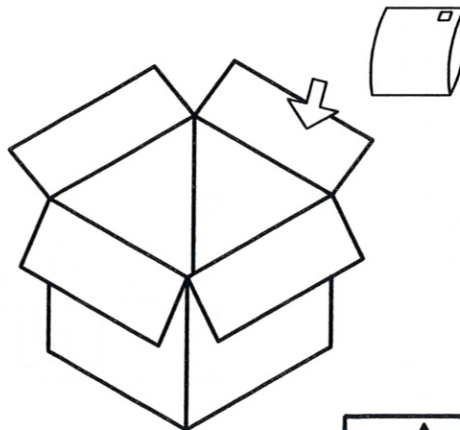


LABEL

SEAL THE BAG



CLOSE CARTON WITH TAPE.



INTO THE CARTON, QT'Y BY OTHER.



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**GOLDENSUNDA TECHNOLOGY CO.,LTD**

TOLERANCE UNLESS OTHERWISE SPECIFIED		PROJ.	TITLE: Wire To Board Wafer 2.54mm 90° DIP Single Row	
.x± 0.35	x.± 2'	APR. C.F.Liao 20150202	PART NO. AD03801XX835A	DWG NO. AD03801XX835A
.xx± 0.25	.x'± 1'	CHK. Abel 20150202	UNITS: mm	CUSTOMER DRAWING
.xxx± 0.15	.xx'± 0.5'	DRA. Michelle 20150202	SIZE: A4	SCALE Free

SHEET 2 / 2 REV A3 V